

Application Data Sheet

Application Information

Application Type::	Regular
Subject Matter::	Utility
Title::	MICROELECTRONICS PACKAGE ASSEMBLY TOOL AND METHOD OF MANUFACTURE THEREWITH
Attorney Docket Number::	24061.59 (TSMC2003-0121)
Request for Early Publication?::	No
Request for Non-Publication?::	No
Suggested Drawing Figure::	1
Total Drawing Sheets::	2
Small Entity::	No
Petition Included?::	No
Secrecy Order in Parent App.?::	No

Applicant Information

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Taiwan
Status::	Full Capacity
Given Name::	Chao-Yuan
Family Name::	Su
City of Residence::	Taiwan
Country of Residence::	Taiwan
Street of Mailing Address::	No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park
City of Mailing Address::	Hsin-Chu
Country of Mailing Address::	Taiwan
Postal or Zip Code of Mailing Address::	300-77

Applicant Authority Type:: Inventor
Primary Citizenship Country:: Taiwan
Status:: Full Capacity
Given Name:: Hsin-Hui
Family Name:: Lee
City of Residence:: Taiwan
Country of Residence:: Taiwan
Street of Mailing Address:: No. 8, Li-Hsin Rd. 6
Science-Based Industrial Park
City of Mailing Address:: Hsin-Chu
Country of Mailing Address:: Taiwan
Postal or Zip Code of Mailing Address:: 300-77

Correspondence Information

Correspondence Customer Number:: 27683
Phone Number:: 972.739.8630
Fax Number:: 214.200.0853
E-Mail Address:: ipdocketing@haynesboone.com

Representative Information

Representative Customer Number::	27683
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Assignee Information

Assignee Name:: Taiwan Semiconductor Manufacturing Co., Ltd.
Street of Mailing Address:: No. 8, Li-Hsin Rd. 6
Science-Based Industrial Park
City of Mailing Address:: Hsin-Chu
Country of Mailing Address:: Taiwan
Postal or Zip Code of Mailing Address:: 300-77